

*DUP*

continuation of U.S. Patent Application No. 08/120,628 filed 9/13/93, abandoned; which is a continuation of U.S. Patent Application No. 08/73,003, filed 6/7/93, abandoned; which is a continuation-in-part of U.S. Patent Application No. 07/709,858, filed 6/4/91, abandoned; and U.S. Patent Application No. 07/788,065, filed 11/5/91, U.S. Patent No. 5,440,240; and U.S. Patent Application No. 07/981,956, filed 11/24/92.

This application is related to U.S. Patent No. 08/406,637 filed 3/30/95.--

On page 9,

line 10, after "bondpad" add--by at least 5000Å,--.

On page 17,

line 14 delete "\_\_\_\_\_ (s.n. 7/898,624),  
for" and substitute --Application serial no. 7/898,624,  
entitled--.

On page 23,

line 13, delete "Serial No. 8/46,675 filed May  
14, 1993," and substitute --No. 5,367,253,--;

line 15, delete "application".

In the claims

Please cancel claims 83, 89, 94 and 95.

*sub.  
S1*

78. (twice amended) An attachment member for making electrical connections for testing [discrete,] unpackaged semiconductor dice, said attachment member comprising:

a substrate for mounting within a test apparatus configured to retain the substrate and a single die and to bias the die against the substrate with a selected contact force;

a contact formed on the substrate including a plurality of raised portions projecting from a surface of the contact